



## Material Content Data Sheet



<b>Sales Product Name</b>				IPL65R660E6		<b>Issued</b>		19. July 2018	
<b>MA#</b>				MA001157984					
<b>Package</b>				PG-VSON-4-1		<b>Weight*</b>		187.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.294	1.76	1.76	17591	17591	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		68		
	non noble metal	zinc	7440-66-6	0.051	0.03		272		
	non noble metal	iron	7439-89-6	1.017	0.54		5432		
wire	non noble metal	copper	7440-50-8	41.300	22.06	22.64	220564	226336	
	non noble metal	copper	7440-50-8	0.684	0.37	0.37	3651	3651	
	encapsulation	organic material	carbon black	1333-86-4	0.220	0.12		1177	
leadfinish	plastics	epoxy resin	-	11.347	6.06		60598		
	inorganic material	silicondioxide	60676-86-0	98.596	52.65	58.83	526553	588328	
	non noble metal	tin	7440-31-5	2.397	1.28	1.28	12804	12804	
plating	noble metal	silver	7440-22-4	0.252	0.13	0.13	1346	1346	
solder	noble metal	silver	7440-22-4	0.075	0.04		403		
	non noble metal	tin	7440-31-5	0.060	0.03		323		
	non noble metal	lead	7439-92-1	2.884	1.54	1.61	15402	16128	
heatspreader	inorganic material	phosphorus	7723-14-0	0.008	0.00		40		
	non noble metal	zinc	7440-66-6	0.030	0.02		161		
	non noble metal	iron	7439-89-6	0.601	0.32		3212		
	non noble metal	copper	7440-50-8	24.418	13.04	13.38	130403	133816	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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